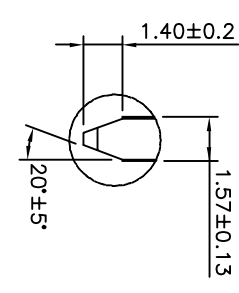
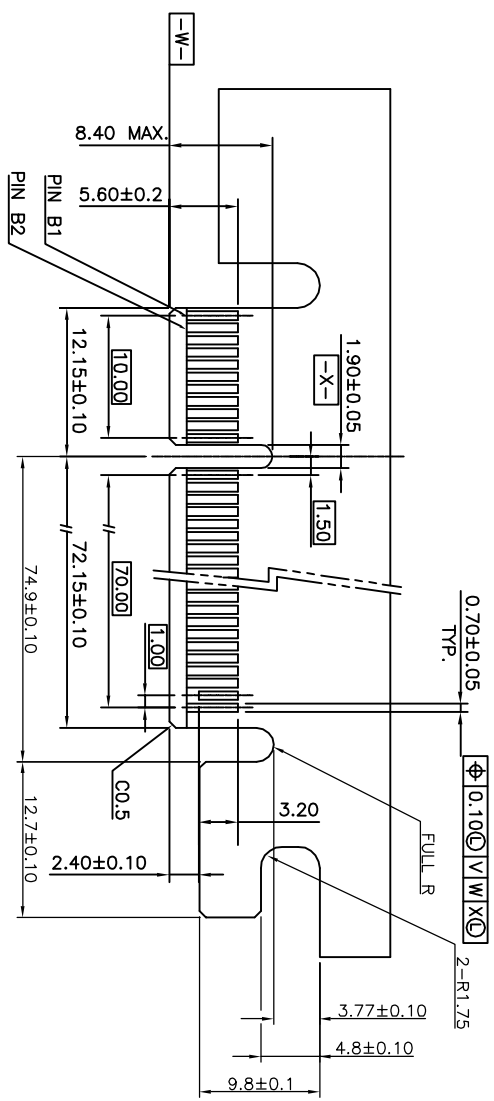


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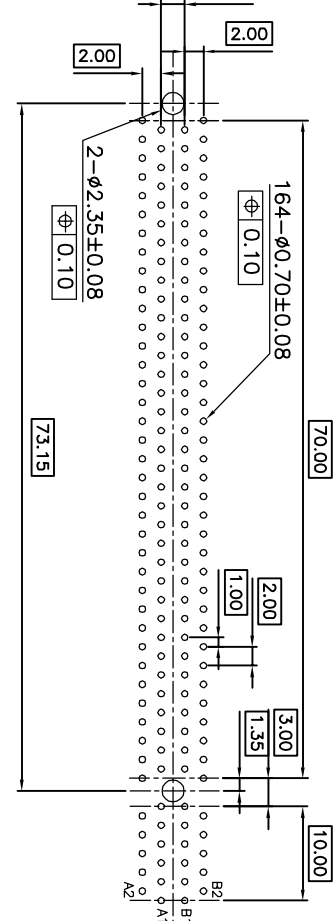
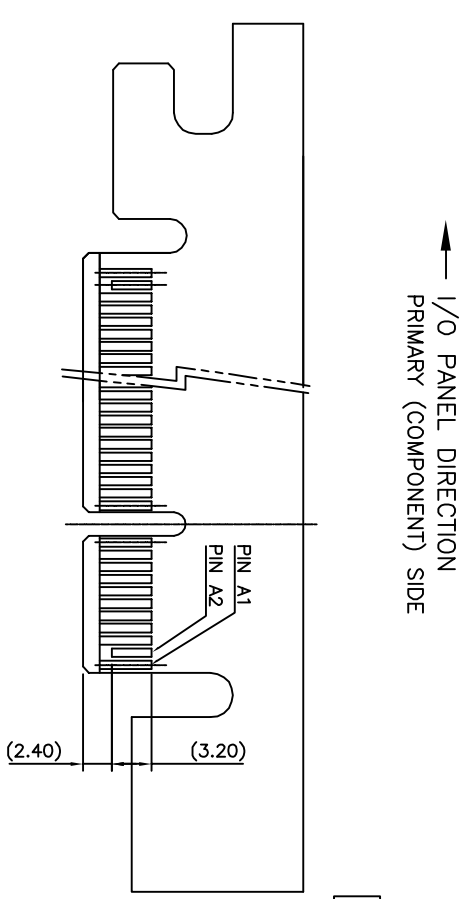
22526

mat'l. code		ttr		ecn no		dr		dtdt		linear		tolerances unless otherwise specified		CUSTOMER COPY		FCI		title		product family		code	
A		T05-0046		J.H		2/23/05		.XX ± 0.25		.XX ± 0.25		.XX ± 0.25		projection		PCI-E INTEGRATED TYPE		EDGE CARD		TWN		1 of 1	
B		T05-0067		J.H		3/28/05		.XXX ± 0.10		.XXX ± 0.10		.XXX ± 0.10		MM		CARD EDGE ASS'Y		EDGE CARD		TWN		1 of 1	
C		T05-0227		J.H		09/30/05		angles		0° ± 2°		0° ± 2°		MM				EDGE CARD		TWN		1 of 1	
D		T06-0187		J.H		11/13/06		dr		JASON HSU		JASON HSU		2/23/05		2/23/05		EDGE CARD		TWN		1 of 1	
E		T07-1125		J.H		08/02/07		engr		STERLING LIN		STERLING LIN		2/23/05		2/23/05		EDGE CARD		TWN		1 of 1	
sheet		revision		E		E		E		E		E		E		E		E		E		E	
index		sheet		1		2		3		3		3		3		3		3		3		3	



SCALE 2:1

ADD-IN CARD EDGE-FINGER DIMENSIONS



RECOMMENDED FOOTPRINT LAYOUT

I/O PANEL DIRECTION  
SECONDARY (SOLDER) SIDE

I/O PANEL DIRECTION  
PRIMARY (COMPONENT) SIDE

mod'l. code	tolerances unless otherwise specified		CUSTOMER COPY	FCI	title	product family	code
itr	ecn no	dr	date	linear	.XX ± 0.25	projection	PCI-E INTEGRATED TYPE
E				angles	φ ± 0.10	MM	CARD EDGE ASS'Y
				dr	JASON HSU 2/23/05	scale	EDGE CARD
				engr	JASON HSU 2/23/05	1:1	
				chr	STERLING LIN 2/23/05	product family	TWIN
				qppd	HC LIU 2/23/05	size dwg no	10046742
sheet	revision					code	2 of 2
index	sheet					sheet	

1 1  
2 2

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3

code code  
22526

4



1 | 2

3

4

NOTES: 1. MATERIAL:

HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0, COLOR IN BLACK.  
LATCHES: THERMOPLASTIC WITH GLASS FIBER, UL94 HB, COLOR IN BLACK.  
CONTACTS: COPPER ALLOY.  
BOARDLOCKS: COPPER ALLOY.

2. FINISH:

CONTACTS: GOLD PLATING ON CONTACT AREA,  
100u"MIN. TIN/LEAD OR 60u" MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS,  
50u"MIN. NICKEL UNDERPLATING OVER ALL.  
BOARDLOCKS : 100u" TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDERTAILS,  
50u"MIN. NICKEL UNDERPLATING OVER ALL.

3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER BY 20 DEGREE.  
4. DURABILITY: 50 CYCLES.

5. RoHS COMPATIBLE PRODUCT SPECIFICATIONS  
a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 2.5um min. MATTE PURE TIN OVER 1.27um MIN. NICKEL UNDERPLATE.

b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C±5C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10046742 -X X X X X X X X LF

APPLICATIONS

BLANK - LEAD CONTAIN FOR PLATING OPTIONS 3,4,5  
LF - LEAD FREE FOR PLATING OPTIONS 0,1,2

HOUSING COLOR OPTIONS

- 1-BLACK FOR BASE & RM
- 2-BLACK FOR BASE & WHITE FOR RM
- 3-BLUE (287U) FOR BASE & RM
- 4-BLUE (297U) FOR BASE & RM

PEGS OPTIONS

- 1-METAL & PLASTIC COMPOUND

TERMINAL PLATING OPTIONS

- 0-50u" Ni: UNDERPLATE
- 30u" Au CONTACT AREA
- 100u" TIN TAIL AREA
- 1-50u" Ni: UNDERPLATE
- 15u" Au CONTACT AREA
- 100u" TIN TAIL AREA
- 2-50u" Ni: UNDERPLATE
- GOLD FLASH CONTACT AREA
- 100u" TIN TAIL AREA
- 3-50u" Ni: UNDERPLATE
- 30u" Au CONTACT AREA
- 100u" TIN/LEAD TAIL AREA
- 4-50u" Ni: UNDERPLATE
- 15u" Au CONTACT AREA
- 100u" TIN/LEAD TAIL AREA
- 5-50u" Ni: UNDERPLATE
- GOLD FLASH CONTACT AREA
- 100u" TIN/LEAD TAIL AREA

TAIL LENGTH OPTION (DIM A)

- 1- 3.10MM
- 2- 2.30MM

PACKAGING OPTIONS

- T-TRAY PACKAGING

- POS OPTIONS
- 3-164

mat'l. code	ecn no	dr	date	linear	tolerances unless otherwise specified	projection	title	product family	code
E				.XX ± 0.25		MM	PCI-E INTEGRATED TYPE CARD EDGE ASSY	EDGE CARD	TWIN
				.XXX ± 0.10					3 of
				0 ±.2					
				dr JASON HSU 2/23/05					
				engr JASON HSU 2/23/05					
				chr STERLING LIN 2/23/05					
				pppl HC LIOU 2/23/05					
sheet	revision								
index	sheet								

1 | 2

3

4

ACAD

code code  
22526